



LEADING AT THE EDGE

TECHNOLOGY AND MANUFACTURING DAY



IDM ADVANTAGE

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DISCLOSURES

Intel Technology and Manufacturing Day 2017 occurs during Intel's "Quiet Period," before Intel announces its 2017 first quarter financial and operating results. Therefore, presenters will not be addressing first quarter information during this year's program.

Statements in this presentation that refer to forecasts, future plans and expectations are forward-looking statements that involve a number of risks and uncertainties. Words such as "anticipates," "expects," "intends," "goals," "plans," "believes," "seeks," "estimates," "continues," "may," "will," "would," "should," "could," and variations of such words and similar expressions are intended to identify such forward-looking statements. Statements that refer to or are based on projections, uncertain events or assumptions also identify forward-looking statements. Such statements are based on management's expectations as of March 28, 2017, and involve many risks and uncertainties that could cause actual results to differ materially from those expressed or implied in these forward-looking statements. Important factors that could cause actual results to differ materially from the company's expectations are set forth in Intel's earnings release dated January 26, 2017, which is included as an exhibit to Intel's Form 8-K furnished to the SEC on such date. Additional information regarding these and other factors that could affect Intel's results is included in Intel's SEC filings, including the company's most recent reports on Forms 10-K, 10-Q and 8-K reports may be obtained by visiting our Investor Relations website at www.intc.com or the SEC's website at www.sec.gov.

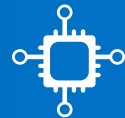
DATA



MEMORY



FPGA



NEW DEVICES



SYSTEMS ARCHITECTURE

SILICON ENGINEERING

PLATFORM DEVELOPMENT

SOFTWARE ENABLING

PROCESS/PRODUCT ALIGNMENT



CLIENT



IOT



CONNECTIVITY



**AUTOMATED
DRIVING**

WAVES OF INNOVATION

PREDICTABLE CADENCE

**CO-OPTIMIZED PROCESS
& ARCHITECTURE**

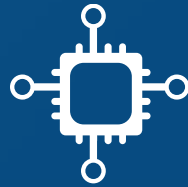
COMPELLING IMPROVEMENTS



CLIENT



SERVER



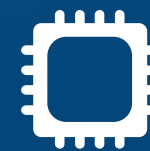
FPGA



NETWORKING



MOBILE



SoCs



AUTOMATED
DRIVING

PRODUCT LEADERSHIP

PROCESS TECHNOLOGY

TRANSISTOR CHARACTERISTICS
METAL INTERCONNECT
PACKAGING & TESTING



PRODUCT DEVELOPMENT

FUNCTIONAL PARTITIONING
IP OPTIMIZATION
POWER/PERFORMANCE/AREA

ANNUAL PRODUCT CADENCE EXAMPLE

2H '15
6TH GEN



15%
BETTER
PERFORMANCE¹

2H '16
7TH GEN



>15%
BETTER
PERFORMANCE²

2H '17
8TH GEN

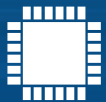


1&2 = Based on SYSmark® 2014 v1.5 (Windows Desktop Application Performance). Comparing 6th Gen (Skylake): i7-6600U, PL1=15W TDP, 2C4T, Turbo up to 3.4GHz, Memory: 2x4GB DDR4-2133, vs. 7th Gen (Kaby Lake): i7-7600U, PL1=15W TDP, 2C4T, Turbo up to 3.9GHz, Memory: 2x4GB DDR4-2133, vs. Estimates for 8th Gen (Kaby Lake U42): PL1=15W and PL2=44W TDP, 4C8T, Turbo up to 4.0GHz. Additional config details: Storage: Intel SSD, Display Resolution: 1920x1080, OS: Windows® 10 TH2. Note: Kaby Lake U42 performance estimates are Pre-Silicon, apply to top bin, and are subject to change. Pre-Si projections have +/- 7% margin of error.

Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors.

Performance tests, such as SYSmark and MobileMark, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products. For more information go to www.intel.com/benchmarks

IP IN MULTIPLE TECHNOLOGIES



CPU



GRAPHICS



MODEM



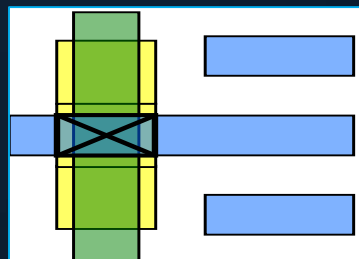
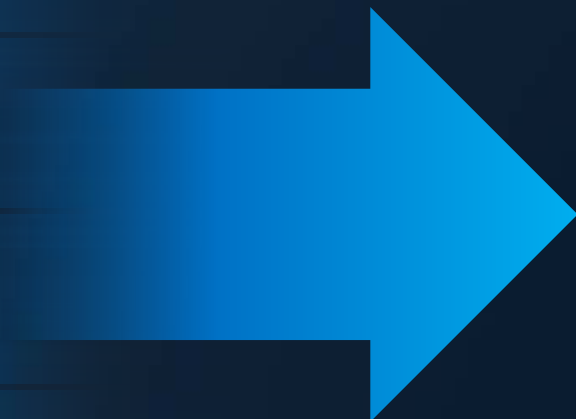
NETWORKING



IO

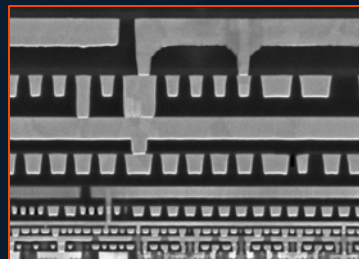


PERIPHERALS



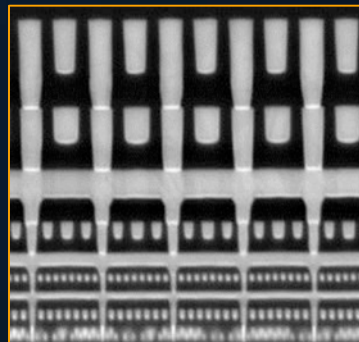
10 NM

WAVES OF 10 NM



14 NM

WAVES OF 14 NM



22 NM

WAVES OF 22 NM

14 NM RICH PORTFOLIO OF PRODUCTS

NETWORKING
2018



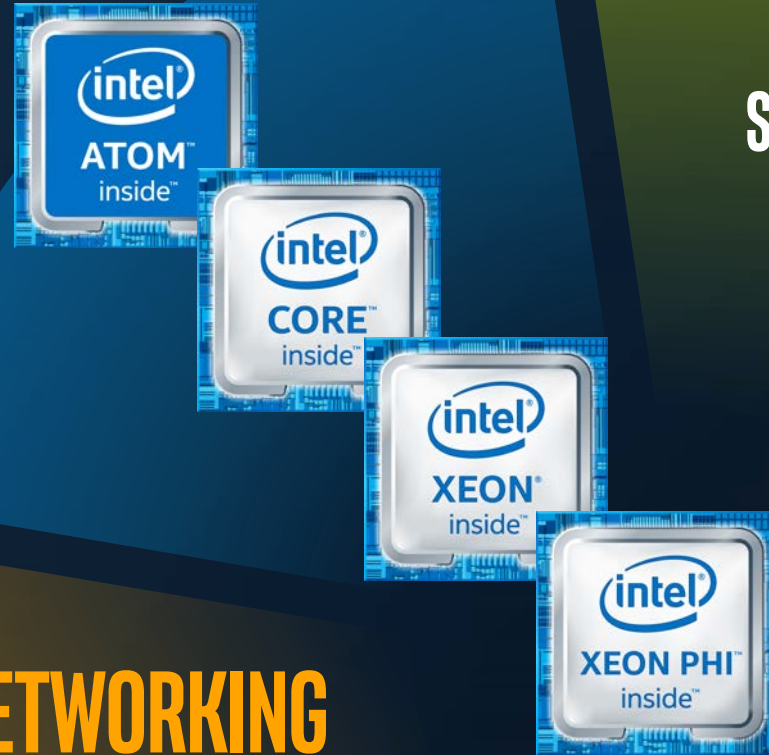
FPGA
STRATIX 10 NOW



PCH
1H 18

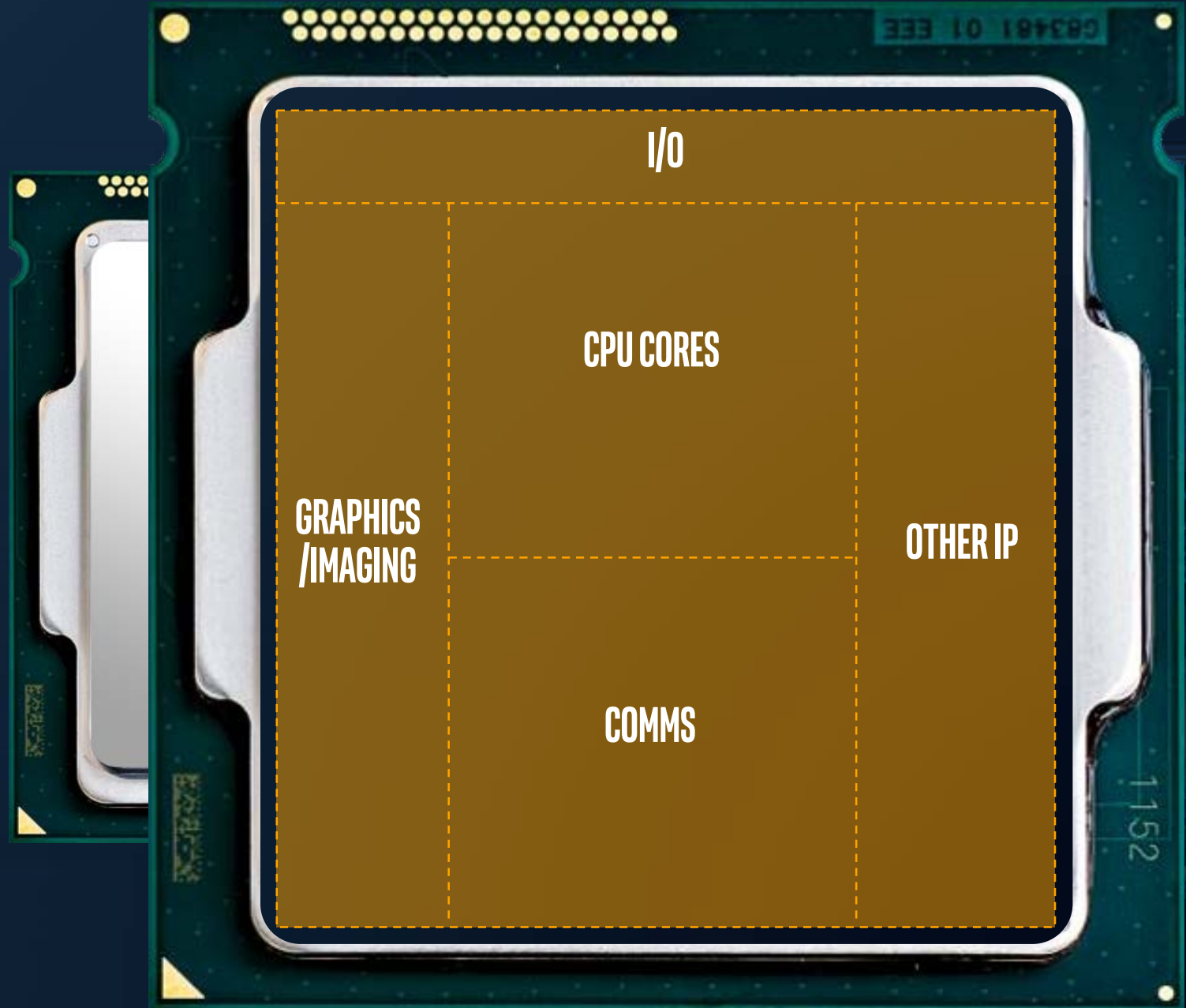


MODEM
EOY '17

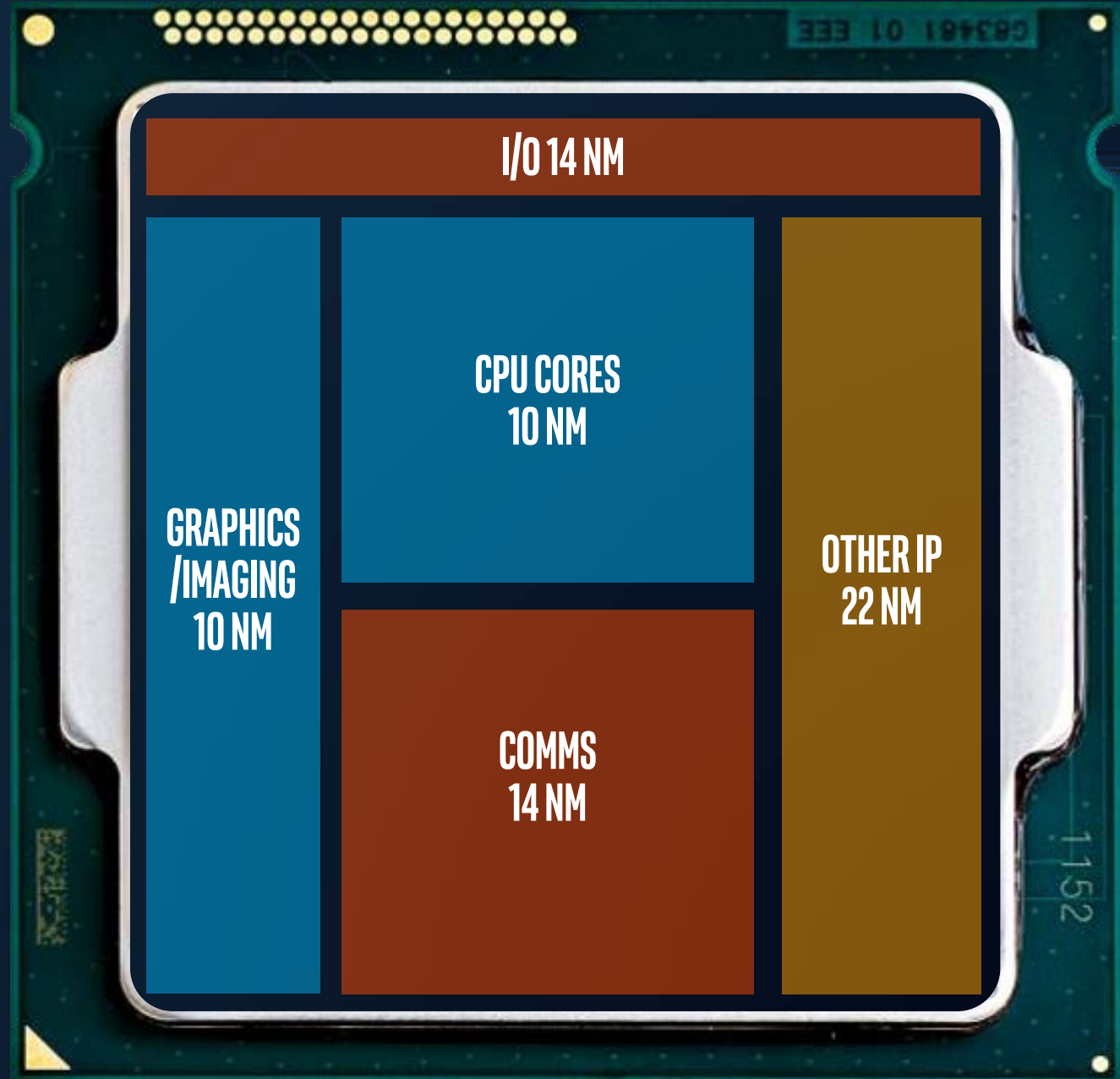




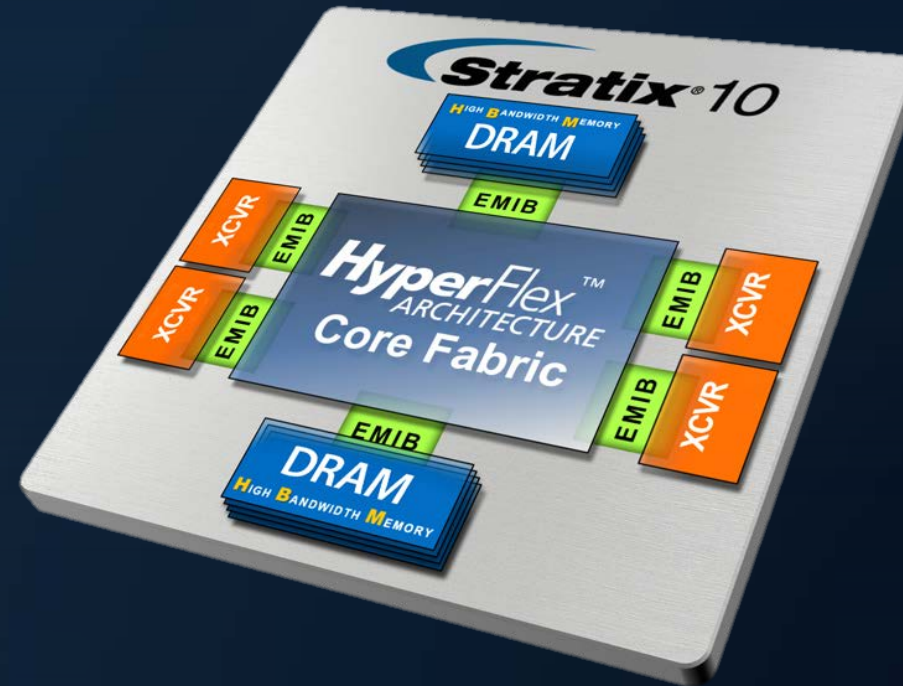
TRADITIONAL MONOLITHIC DESIGN



“MIX AND MATCH” HETEROGENEOUS DESIGN



HETEROGENEOUS EXAMPLE

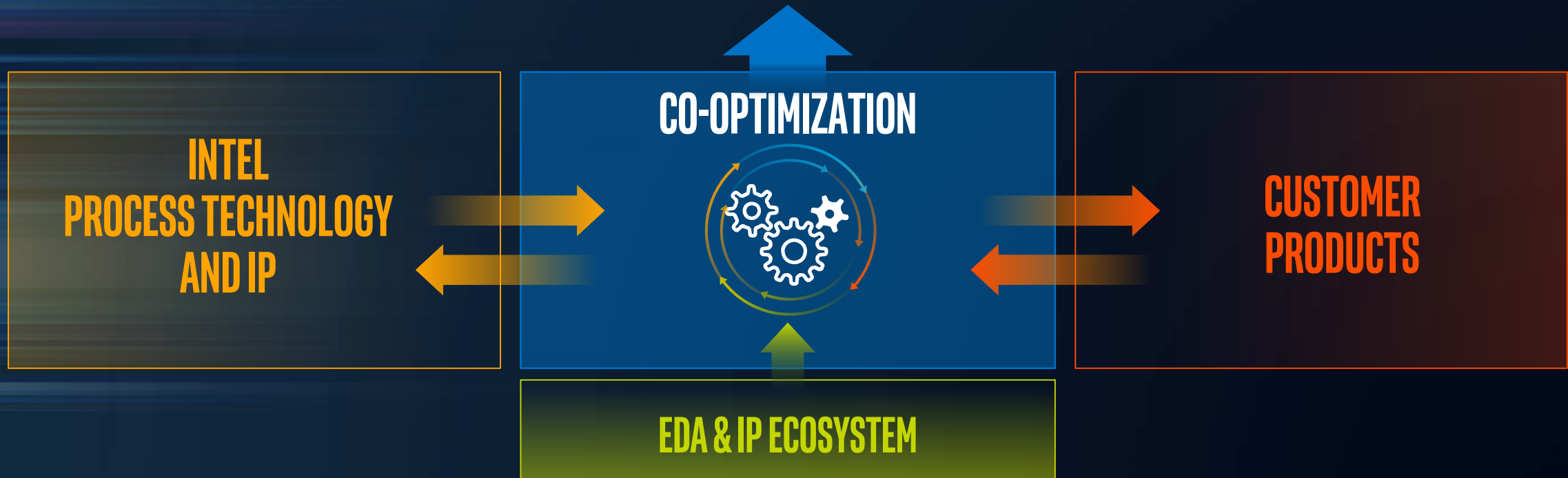


Intel Stratix®10 FPGA

FOUNDRY



PRODUCT LEADERSHIP



**CO-OPTIMIZED
PROCESS
& ARCHITECTURE**

+

ANNUAL CADENCE

+

FOUNDRY

=

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